

Application No.: 10/612,608

Docket No.: JCLA8671-1

AMENDMENTIN THE CLAIMS

Please amend the claims according to the following listing of claims and substitute it for all prior versions and listings of claims in the application.

Claims 1-6 (cancelled)

7. (currently amended) A method of fabricating organic electroluminescence panel comprising the steps of

providing a substrate;

forming a plurality of first electrodes on the substrate, wherein the first electrode includes a driving region and at least an interconnection region and the interconnection region is protruded from the driving region;

forming at least a patterned organic ~~electroluminescence panel~~ light-emitting layer on the substrate, wherein the patterned organic light-emitting layer exposes the interconnection region;

forming a hole injection layer between the first electrodes and the organic light-emitting layer after the formation of the first electrodes but before the formation of the light-emitting layer;

forming a plurality of second electrodes on the organic light-emitting layer; and

forming a plurality of poly solder interconnections on the interconnection region and on the second electrodes.

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Claims 8-17 (cancelled)

18. (currently amended) The method of claim 7, further comprising the step of forming a hole transmitting layer between the hole injection layer and the organic light-emitting layer after the formation of the electron injection layer but before the formation of the light emitting layer.

19. (original) The method of claim 7, further comprising the step of forming an electron transmitting layer between the organic light-emitting layer and the second electrode after the formation of the organic light-emitting layer but before the formation of the second electrodes.

20. (original) The method of claim 19, further comprising the step of forming an electron injection layer between the electron transmitting layer and the second electrodes after the formation of the electron transmitting layer but before the formation of the cathode.

21. (original) The method of claim 7, wherein the poly solder interconnections include low re-flow temperature materials.

22. (original) The method of claim 7, wherein the poly solder interconnections are in area array.